

RoHS & FDA Compliance of material used in ROTRONIC products

The table declares the materials used for ROTRONIC probes and transmitters as well as the absence of certain materials.

Material/Code	Use	Used for
ABS	Yes	Housings of transmitters
Aluminium	No	No Aluminium is used
Brass, Nickel coated	Yes	Filter holders of industrial probes
Fluorocarbon (Radox)	Yes	System cable for high temperatures
Polycarbonate	Yes	Housings of transmitters
PPS (PEEK 151 G)	Yes	Industrial probes HygroClip IC-xx
PTFE (Teflon) / FEP	Yes	System cables for PPS probes
<u>RoHS List:</u> Mercury, Lead, Cadmium, hexavalent chromium, PBB, PBDE	No	With the exception of traces of lead, none of the substances are used in our products. The products are soldered lead free. Only a few components such as ASIC's may contain traces of lead due to technical non-feasibility without lead (Exception to RoHS, annex § 5). Stock shall be used up till July 1 st 2006. New ASIC is in development and will be lead free.
Silicone	No	No silicone is used
TPU (extruded Polyester)	Yes	System cables used for extension cables etc.
V2A Steel 1.4305 X 12 CR Ni S 18 8 AFNOR: Z 10 CNF 18-9 AISI:302	Yes	Used for industrial probes HygroClip IM and HygroClip IE series, lathe work parts
V4A Steel 1.4401 X 5 CR Ni Mo 18 10 AFNOR: Z 6 CND 17-11 AISI: 316	Yes	Wire mesh and sinter filters, housings of HygroClip EX probes
Wood	No	No wooden boxes are used for packaging

Note: PPS (PEEK 151 G) is manufactured by Victrex and is fully compliant to


FDA CFR 21 Part 177.2415, Sanitary Standard 20-19 and EEC 93/9.


The colorant does not contain cadmium, lead or Diaryl pigments and also complies to the

EC norms 94/62/EWG which limit the contents of heavy metals.

These materials may be used safely in the food industry.

ROTRONIC AG


Daniel Ritler
Head of Department


Peter Mueller
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Bassersdorf, January 27, 2006

RoHS statement

TO WHOM IT MAY CONCERN

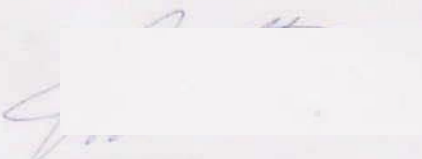
By the present letter ROTRONIC AG declares that ROTRONIC will fulfil the regulation concerning Lead-free soldering by the 1st July 2006 for all ROTRONIC products.

Until now (1st September 2003) all manually soldered parts are already Pb-free. All SMD components will be adapted by 1st June 2005.

ROTRONIC is continuously pushing its supplier for e.g. PCB (Printed Circuit Boards) to supply lead-free produced material. There are only a small number of suppliers who didn't change the technology yet. Should the suppliers not be ready to supply the PCB's already 6 month before the 1st July 2006 the supplier will be changed.

ROTRONIC also confirms that Cd, Hg, Cr, PBB, PBDE is not used in its production at all.

ROTRONIC AG


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